CMPD7000E

ENHANCED SPECIFICATION SURFACE MOUNT DUAL, IN SERIES SILICON SWITCHING DIODES





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMPD7000E is an Enhanced version of the CMPD7000 Dual, Series Configuration, Ultra-High Speed Switching Diode. This device is manufactured by the epitaxial planar process, in an epoxy molded surface mount SOT-23 package, designed for high speed switching applications.

MARKING CODE: C5CE

FEATURED ENHANCED SPECIFICATIONS:

- ♦ BV_R from 100V min to 120V min.
- ♦ V_F from 1.1V max to 1.0V max.

MAXIMUM RATINGS: (TA=25°C)	SYMBOL		UNITS
♦ Peak Repetitive Reverse Voltage	V_{RRM}	120	V
Average Forward Current	IO	200	mA
Peak Forward Current	I _{FM}	500	mA
Power Dissipation	P_{D}	350	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	ΘΙΔ	357	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_{R}	V _R =50V			300	nA
I_{R}	V _R =50V, T _A =125°C			100	μΑ
I_{R}	V _R =100V			500	nA
♦ BV _R	I _R =100μA	120	150		V
♦ V _F	I _F =1.0mA	0.55	0.59	0.65	V
♦ v _F	I _F =10mA	0.67	0.72	0.77	V
♦ v _F	I _F =100mA	0.85	0.91	1.0	V
CT	V _R =0, f=1.0MHz		1.5	2.6	pF
t _{rr}	$I_R = I_F = 10$ mA, $R_L = 100\Omega$, Rec. to 1.0mA		2.0	4.0	ns

[♦] Enhanced Specification

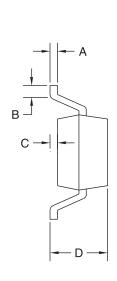
CMPD7000E

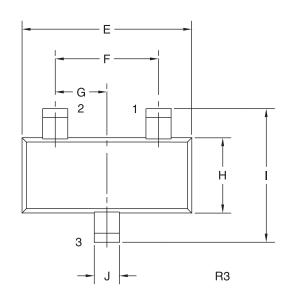
ENHANCED SPECIFICATION SURFACE MOUNT

DUAL, IN SERIES
SILICON SWITCHING DIODES

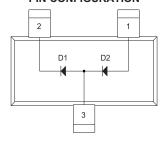


SOT-23 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



LEAD CODE:

- 1) Anode D2
- 2) Cathode D1
- 3) Anode D1, Cathode D2

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DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.003	0.007	0.08	0.18			
В	0.006	-	0.15	-			
С	-	0.005	-	0.13			
D	0.035	0.043	0.89	1.09			
E	0.110	0.120	2.80	3.05			
F	0.075		1.90				
G	0.037		0.95				
Н	0.047	0.055	1.19	1.40			
	0.083	0.098	2.10	2.49			
J	0.014	0.020	0.35	0.50			

SOT-23 (REV: R3)

R4 (27-January 2010)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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